

AMENDMENTS TO THE CLAIMS

This Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A wiring substrate manufacturing method comprising a step of forming a wiring of a wiring substrate by an exposure treatment using a photomask which has a shade pattern formed on a plate, said shade pattern containing at least nano particles and a binder.

2. (Previously Presented) The wiring substrate manufacturing method according to claim 1, wherein said nano particles comprise a black pigment, and the wiring substrate manufacturing method further comprises a step of forming each of said shade patterns on said plate by printing a shade material containing said black pigment of 30% or less.

3. (Previously Presented) The wiring substrate manufacturing method according to claim 1, wherein said shade pattern correspond corresponds to said wirings, respectively.

4. (Previously Presented) The wiring substrate manufacturing method according to claim 1, wherein an area of

said shade pattern is relatively smaller than an area of a light transmission region having no shade pattern.

5. (Previously Presented) The wiring substrate manufacturing method according to claim 1, further comprising the steps of:

forming a line pattern for forming said wiring, in a thickness direction of a wiring substrate main body; and

forming a hole pattern which is a pattern for forming said wirings and which connects, to one another, line patterns located on difference different wiring layers.

6. (Original) The wiring substrate manufacturing method according to claim 1, wherein said nano particles consist of carbon.

7. (Original) The wiring substrate manufacturing method according to claim 1, further comprising a step of mounting one or a plurality of electronic components on a first surface of said substrate.

8. (Original) The wiring substrate manufacturing method according to claim 7, further comprising a step of mounting, while a second surface opposite to the first surface of said substrate faces a printed wiring substrate, the substrate on

which said one or plurality of electronic components are mounted, on a printed wiring substrate.

9-17. (Canceled).

18. (Previously Presented) The wiring substrate manufacturing method according to Claim 1, wherein the plate having said shade pattern formed thereon is a glass plate.

19. (New) The wiring substrate manufacturing method according to Claim 1, wherein the nano-particles scatter light used by the exposure treatment.